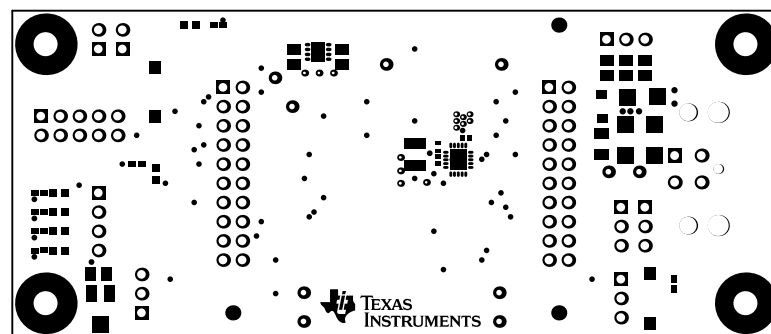
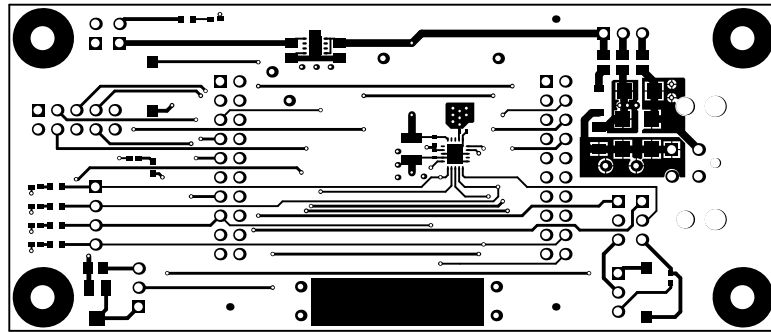


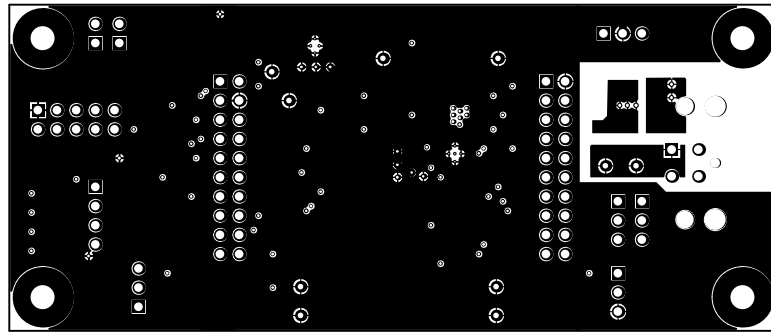
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/1/2014 2:13:03 PM	TEXAS INSTRUMENTS	



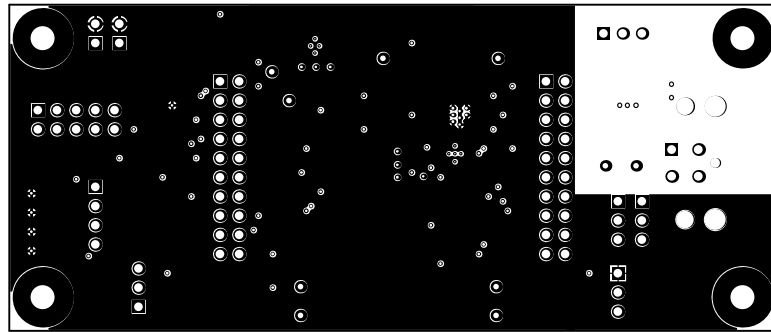
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/1/2014 2:13:05 PM	TEXAS INSTRUMENTS	



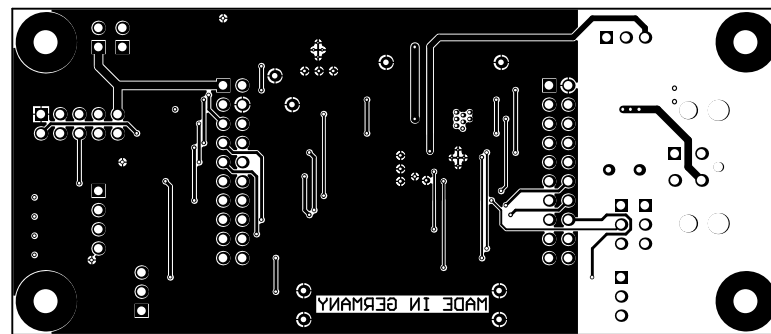
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/1/2014 2:13:08 PM	TEXAS INSTRUMENTS	



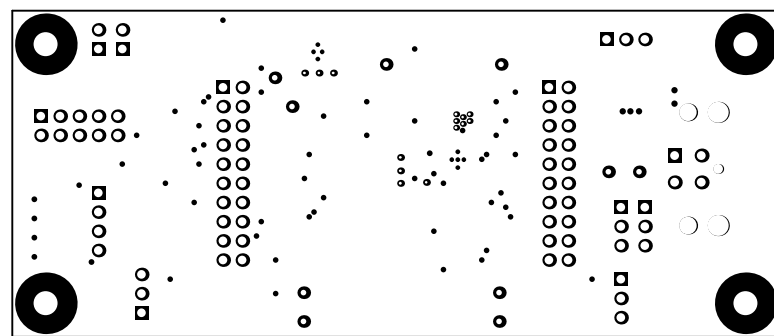
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 12/1/2014 2:13:10 PM	TEXAS INSTRUMENTS	



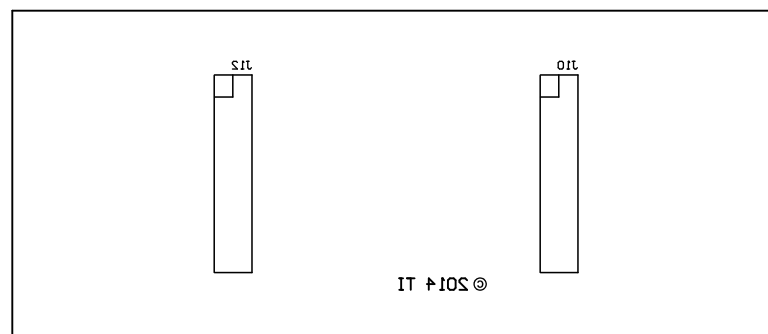
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 12/1/2014 2:13:13 PM	TEXAS INSTRUMENTS	



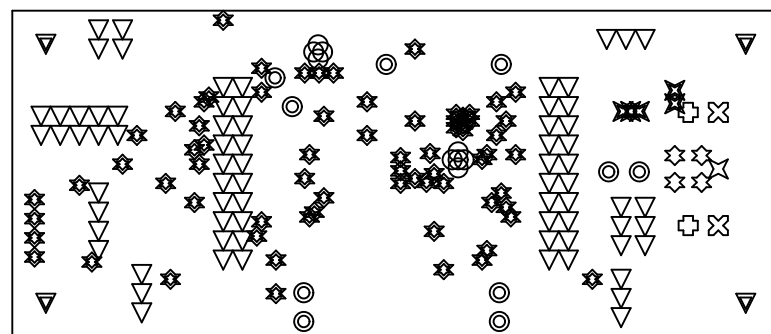
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/1/2014 2:13:15 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/1/2014 2:13:17 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/1/2014 2:13:20 PM	TEXAS INSTRUMENTS	

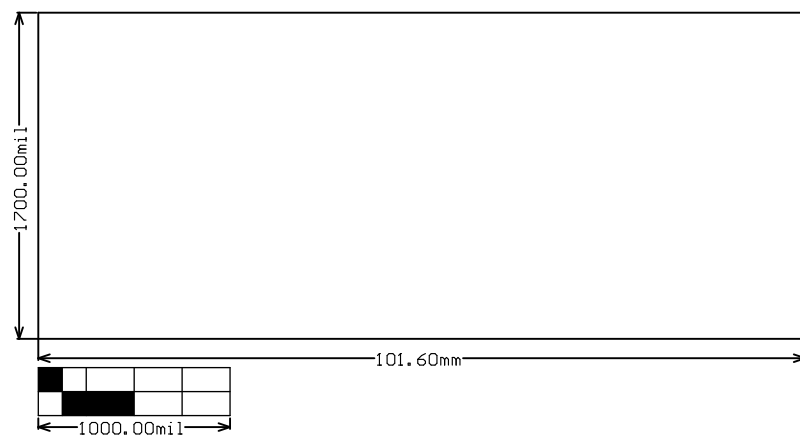
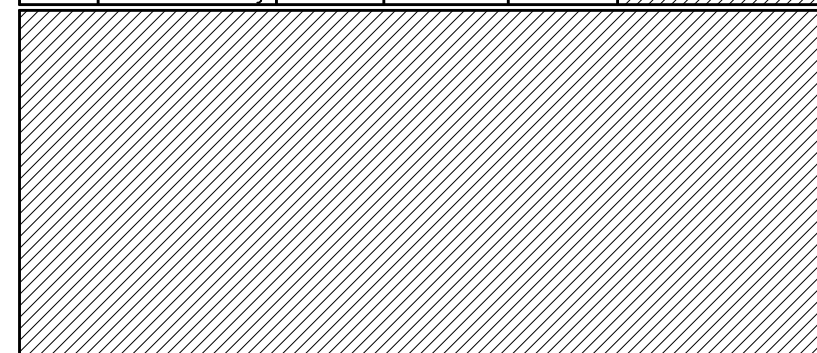


Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✕	1	51.18mil (1.300mm)	NPTH	Round
⊙	2	92.52mil (2.350mm)	NPTH	Round
⊗	2	110.24mil (2.800mm)	NPTH	Round
▽	4	125.98mil (3.200mm)	NPTH	Round
○	9	7.87mil (0.200mm)	PTH	Round
★	70	15.00mil (0.381mm)	PTH	Round
✕	5	17.00mil (0.432mm)	PTH	Round
●	10	30.00mil (0.762mm)	PTH	Round
▽	73	45.28mil (1.150mm)	PTH	Round
☆	4	47.24mil (1.200mm)	PTH	Round
	180 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/1/2014 2:13:22 PM	TEXAS INSTRUMENTS	

STANDARD 4 LAYER FR4 STACKUP - DISREGARD NUMBERS IN THE TABLE

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder		1.00mil	1	
3	Top Layer	Copper	1.00mil		
4	Dielectric1		1.00mil	1	
5	GND	Copper	1.00mil		
6	Dielectric 3		1.00mil	1	
7	VCC	Copper	1.00mil		
8	Dielectric 2		1.00mil	1	
9	Bottom Layer	Copper	1.00mil		
10	Bottom Solder		1.00mil	1	
11	Bottom Overlay				



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00339	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/1/2014 2:13:25 PM	TEXAS INSTRUMENTS	

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